# 2SC3829

# Silicon NPN epitaxial planar type

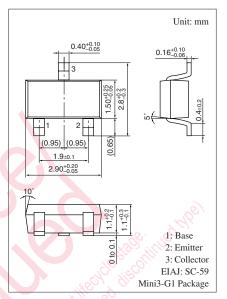
### For UHF band low-noise amplification

#### ■ Features

- Low noise figure NF
- High gain
- High forward transfer gain  $|S_{21e}|^2$
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	15	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	10	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	2	V	
Collector current	$I_{C}$	80	mA	
Collector power dissipation	P <sub>C</sub>	200	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	

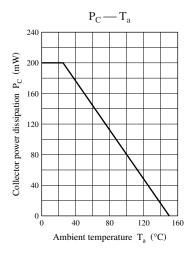


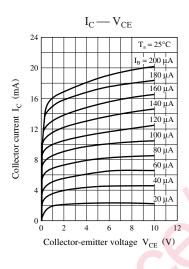
Marking Symbol: 3M

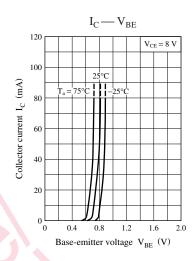
## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

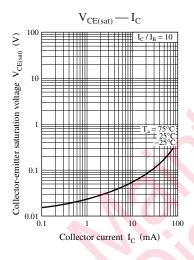
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = 10  \mu \text{A},  I_{\rm E} = 0$	15			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 100 \ \mu A, I_B = 0$	10			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 10 \text{ V}, I_{E} = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 2 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}$	50	150	300	_
Transition frequency	$f_T$	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$	5	6		GHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		0.7	1.2	pF
(Common base, input open circuited)	(g)					
Forward transfer gain	S <sub>21e</sub>   2	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$	10.0	13.5		dB
Maximum unilateral power gain	$G_{UM}$	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$		15		dB
Noise figure	NF	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 0.8 \text{ GHz}$			2	dB

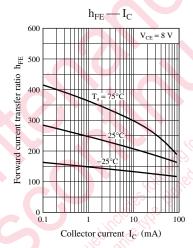
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

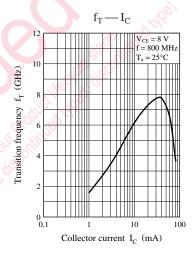


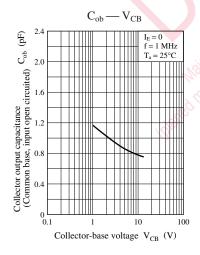


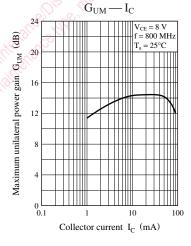


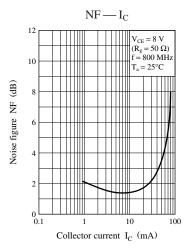












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